

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. - 2. (Cancelled).

3. (Previously presented) The cleaning composition according to Claim 13, which includes the alkaline compound, in an amount up to 99.999% by weight.

4. (Previously presented) The cleaning composition according to Claim 3, wherein the alkaline compound is free from metallic element.

5. (Original) The cleaning composition according to Claim 3, wherein the alkaline compound is at least one compound selected from the group consisting of alkyl amines, alkanol amines, polyamines, hydroxyl amine compounds, cyclic amines, and quaternary ammonium salts.

6. (Previously presented) The cleaning composition according to Claim 13, which includes the organic solvent, in an amount up to 95% by weight.

7. (Previously presented) The cleaning composition according to Claim 13, further comprising a corrosion inhibitor.

8. (Cancelled).

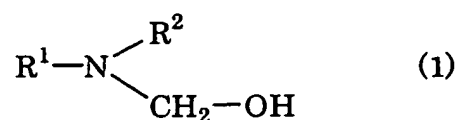
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9. (Currently amended) The cleaning composition according to Claim 138, wherein the amine polymer is at least one polymer selected from the group consisting of polyallylamines, polyethyleneimines and polyvinylamines.

10. (Previously presented) The cleaning composition according to Claim 13, further comprising a compound having a hydroxymethylamino structure represented by the following formula (1):

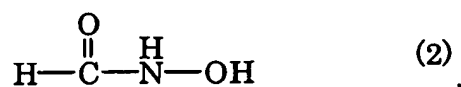


wherein R¹ and R² are each independently hydrogen or substituent having 1 to 12 carbon atoms, R¹ and R² optionally being bonded to each other to form together with nitrogen a ring structure having 2 to 12 carbon atoms.

11. (Previously presented) The cleaning composition according to Claim 13, further comprising water.

12. (Withdrawn) A method for cleaning a substrate of semiconductor integrated circuits or liquid crystal display devices, the method comprising a step of bringing the substrate into contact with the cleaning composition as defined in Claim 13.

13. (Currently amended) A cleaning composition, adapted for removing photoresists from a substrate, comprising 0.001 to 60% by weight of N-hydroxyformamide represented by the following formula (2):



0 to 99.999% by weight of an alkaline compound, and

0 to 95% by weight of an organic solvent, and

further comprising an amine polymer having an average molecular weight of 250 or more.

14. (Currently amended) The cleaning composition according to Claim 13, consisting essentially of 0.001 to 60% by weight of the N-hydroxyformamide, 0 to 99.999% by weight of the alkaline compound, ~~and~~ 0 to 95% by weight of the organic solvent and 0.0001 to 30% by weight of the amine polymer.

15. (Previously presented) The cleaning composition according to Claim 13, which includes 0.01 to 80% by weight of the alkaline compound.

16. (Previously presented) The cleaning composition according to Claim 15, which includes 20 to 80% by weight of the organic solvent.

17. (Previously presented) The cleaning composition according to Claim 16, wherein said organic solvent is a water-soluble organic solvent.

18. (Previously presented) The cleaning composition according to Claim 16, which includes 3 to 40% by weight water.